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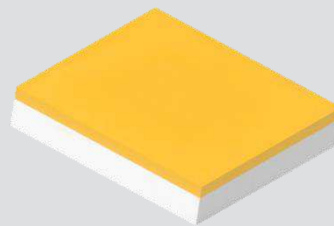
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Middle Power LED Series Flip Chip Package

LM101B



New technology provides high performance and energy conservation

Features & Benefits

- Greater freedom of design with compact package size
- High degree of reliability with plastic-free structure
- Low thermal resistance
- High efficiency providing optimized solution

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1. Characteristics

a) Absolute Maximum Rating

Item	Symbol	Rating	Unit	Condition
Operating Temperature	T_a	-40 ~ +105	°C	-
Storage Temperature	T_{stg}	-40 ~ +120	°C	-
LED Junction Temperature	T_j	125	°C	-
Forward Current	I_F	350	mA	-
Assembly Process Temperature	-	260 <10	°C s	-
ESD (HBM)	-	±2	kV	-

b) Electro-optical Characteristics ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$)

Item	Unit	Rank	Bin	Min.	Typ.	Max.
Forward Voltage (V_F)	V	6E	6A	2.7	-	2.9
			AE	2.9	-	3.1
Reverse Voltage (@ $-10 \mu\text{A}$)	V			-10.0	-	-
Color Rendering Index (R_a)	-	8		80	-	-
Special CRI (R9)	-			0	-	-
Thermal Resistance (junction to chip point)	K/W			-	2	-
Beam Angle	$^\circ$			-	120	-

Note: Samsung maintains measurement tolerance of : Forward voltage = $\pm 0.1 \text{ V}$, Luminous flux = $\pm 5 \%$, CRI = ± 3 , R9 = ± 6.5

c) Luminous Flux Characteristics ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$)

Item	CRI	Nominal CCT (K)	SA		SB		SC		SD		SE		SF		SG		SH	
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
			43	47	47	51	51	55	55	59	59	63	63	67	67	71	71	75
Luminous Flux (Φ_v)	70	2700																
		3000																
		3500																
		4000																
		5000																
		5700																
		6500																
	80	2700																
		3000																
		3500																
		4000																
		5000																
		5700																
		6500																
	90	2700																
		3000																
		3500																
		4000																
5000																		

Note:

- 1) The LM101B is tested in pulsed condition at rated test current (10 ms pulse width)
- 2) Calculated flux values are for reference only
- 3) Samsung maintains measurement tolerance of: luminous flux = $\pm 5 \%$

2. Product Code Information ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$)

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
S	C	P	8	W	T	7	8	H	E	L	1	W	L	S	0	6	E

Digit	PKG Information	Code	Specification
1 2 3	Samsung Chip	SCP	
4	CRI	7 8 9	Min. 70 Min. 80 Min. 90
5	CCT (K)	W V U T R Q P	2700 3000 3500 4000 5000 5700 6500
6	Chip Shape	T	Square
7 8 9	Chip Code	78H	
10 11 12	Product Purpose	EL1	FeC for Lighting
13	CCT (K)	W V U T R Q P	2700K 3000K 3500K 4000K 5000K 5700K 6500K
14	MacAdam Step	L U	Single Bin for MacAdam 5-step L(MacAdam 5-step Bin) Single Bin for MacAdam 3-step U(MacAdam 3-step Bin)
15 16	Luminous Flux (lm)	S0	Bin Code: SY, SZ, SA, SB, SC, SD, SE, SF, SG, SH
17 18	Forward Voltage (V)	6E	2.7~3.1 Bin Code: 6A 2.7~2.9 AE 2.9~3.1

a) Luminous Flux Bins ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$)

CRI (R_a) Min.	Nominal CCT (K)	Product Code	Flux Bin	Flux Range (Φ_v , lm)
70	2700	SCP7WT78HEL1W☆S06E	SE	59 ~ 63
			SF	63 ~ 67
	3000	SCP7VT78HEL1V☆S06E	SF	63 ~ 67
			SG	67 ~ 71
	3500	SCP7UT78HEL1U☆S06E	SF	63 ~ 67
			SG	67 ~ 71
	4000	SCP7TT78HEL1T☆S06E	SG	67 ~ 71
			SH	71 ~ 75
	5000	SCP7RT78HEL1R☆S06E	SG	67 ~ 71
			SH	71 ~ 75
	5700	SCP7QT78HEL1Q☆S06E	SF	63 ~ 67
			SG	67 ~ 71
	6500	SCP7PT78HEL1P☆S06E	SF	63 ~ 67
			SG	67 ~ 71

Note: “☆” can be “L” (Single bin for MacAdam 5-step), “U” (Single bin for MacAdam 3-step)

a) Luminous Flux Bins ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$)

CRI (R_a) Min.	Nominal CCT (K)	Product Code	Flux Bin	Flux Range (Φ_v , lm)
80	2700	SCP8WT78HEL1W☆S06E	SD	55 ~ 59
			SE	59 ~ 63
	3000	SCP8VT78HEL1V☆S06E	SE	59 ~ 63
			SF	63 ~ 67
	3500	SCP8UT78HEL1U☆S06E	SE	59 ~ 63
			SF	63 ~ 67
	4000	SCP8TT78HEL1T☆S06E	SF	63 ~ 67
			SG	67 ~ 71
	5000	SCP8RT78HEL1R☆S06E	SF	63 ~ 67
			SG	67 ~ 71
	5700	SCP8QT78HEL1Q☆S06E	SE	59 ~ 63
			SF	63 ~ 67
	6500	SCP8PT78HEL1P☆S06E	SE	59 ~ 63
			SF	63 ~ 67

Note: “☆” can be “L” (Single bin for MacAdam 5-step) “U” (Single bin for MacAdam 3-step)

a) Luminous Flux Bins ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$)

CRI (R_a) Min.	Nominal CCT (K)	Product Code	Flux Bin	Flux Range (Φ_v , lm)
90	2700	SCP9WT78HEL1W☆S06E	SA	43 ~ 47
			SB	47 ~ 51
	3000	SCP9VT78HEL1V☆S06E	SA	43 ~ 47
			SB	47 ~ 51
	3500	SCP9UT78HEL1U☆S06E	SB	47 ~ 51
			SC	51 ~ 55
	4000	SCP9TT78HEL1T☆S06E	SB	47 ~ 51
			SC	51 ~ 55
	5000	SCP9RT78HEL1R☆S06E	SB	47 ~ 51
			SC	51 ~ 55

Note: “☆” can be “L” (Single bin for MacAdam 5-step), “U” (Single bin for MacAdam 3-step)

b) Color Bins ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ °C}$)

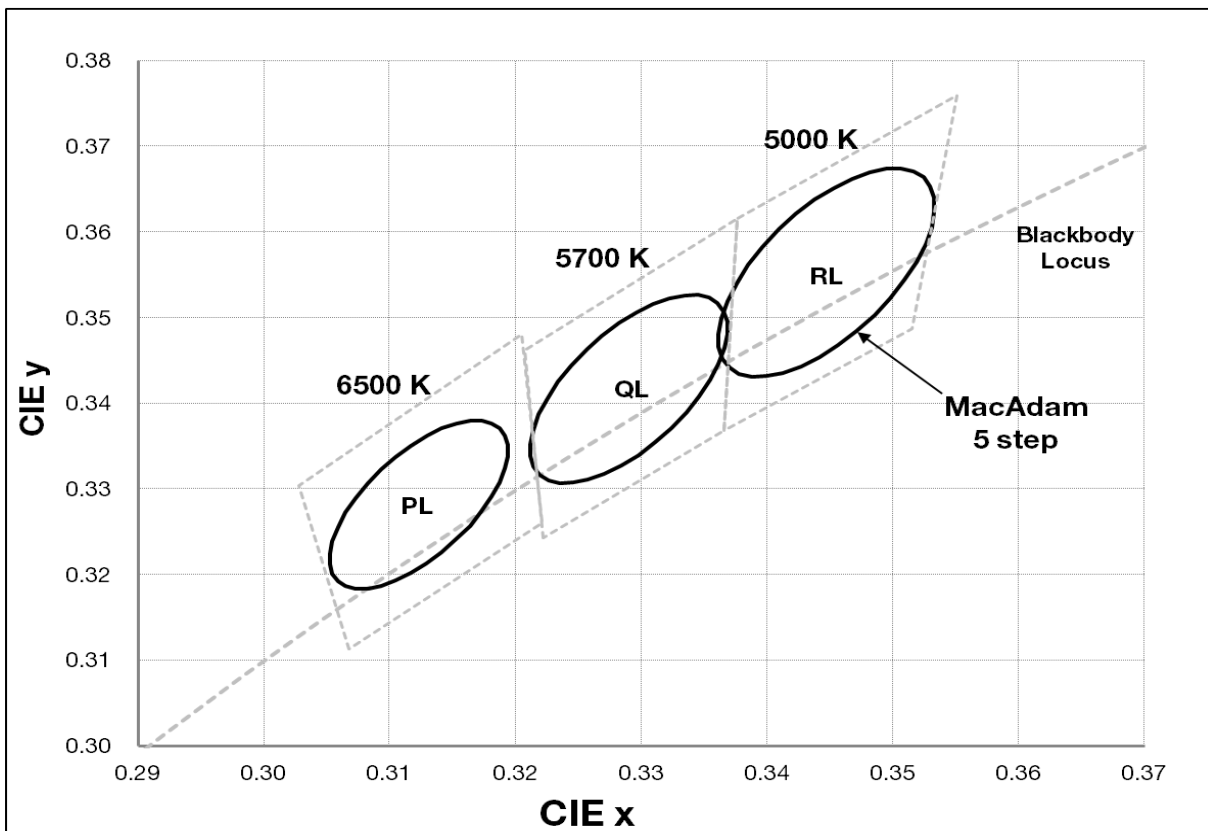
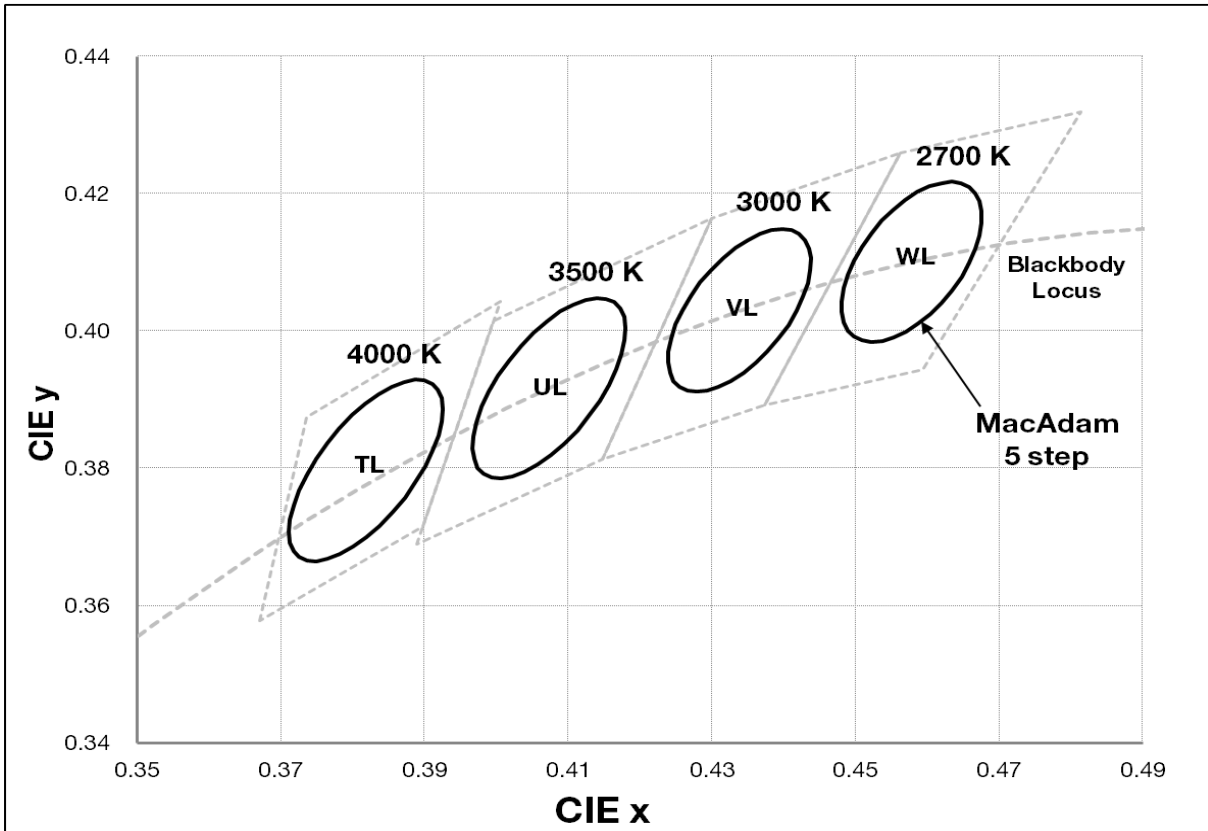
CRI Min	Nominal CCT (K)	Product Code	Color Rank	Chromaticity Bins
70	2700	SCP7WT78HEL1W☆S06E	VL	VL
			VU	VU
	3000	SCP7VT78HEL1V☆S06E	VL	VL
			VU	VU
	3500	SCP7UT78HE1U☆S06E	UL	UL
			UU	UU
	4000	SCP7TT78HEL1T☆S06E	TL	TL
			TU	TU
	5000	SCP7RT78HEL1R☆S06E	RL	RL
			RU	RU
	5700	SCP7QT78HEL1Q☆S06E	QL	QL
			QU	QU
	6500	SCP7PT78HEL1P☆S06E	PL	PL
			PU	PU
80	2700	SCP8WT78HEL1W☆S06E	WL	WL
			WU	WU
	3000	SCP8VT78HEL1V☆S06E	VL	VL
			VU	VU
	3500	SCP8UT78HEL1U☆S06E	UL	UL
			UU	UU
	4000	SCP8TT78HEL1T☆S06E	TL	TL
			TU	TU
	5000	SCP8RT78HEL1R☆S06E	RL	RL
			RU	RU
	5700	SCP8QT78HEL1Q☆S06E	QL	QL
			QU	QU
	6500	SCP8PT78HEL1P☆S06E	PL	PL
			PU	PU
90	2700	SCP9WT78HEL1W☆S06E	WL	WL
			WU	WU
	3000	SCP9VT78HEL1V☆S06E	VL	VL
			VU	VU
	3500	SCP9UT78HEL1U☆S06E	UL	UL
			UU	UU
	4000	SCP9TT78HEL1T☆S06E	UL	UL
			UU	UU
	5000	SCP9RT78HEL1R☆S06E	UL	UL
			UU	UU

Note: “☆” can be “L” (Single bin for MacAdam 5-step), “U” (Single bin for MacAdam 3-step)

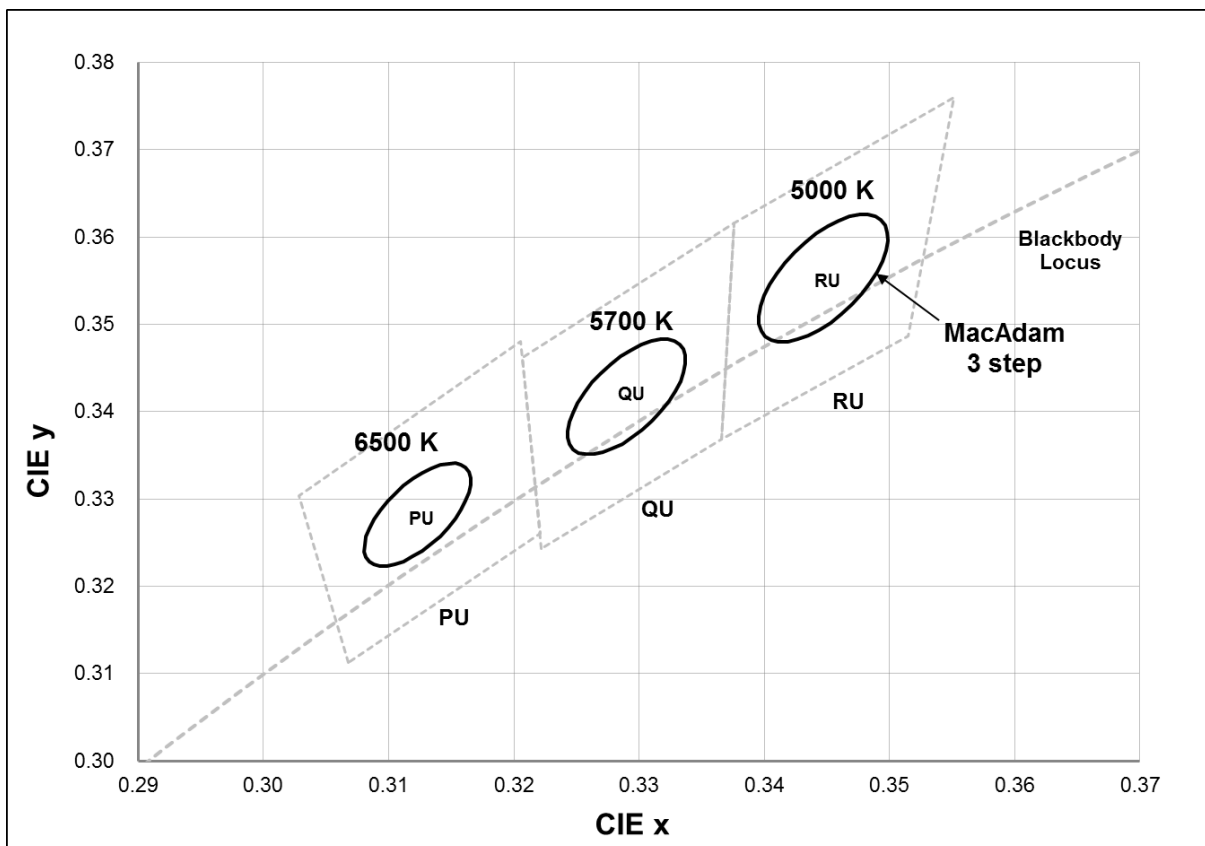
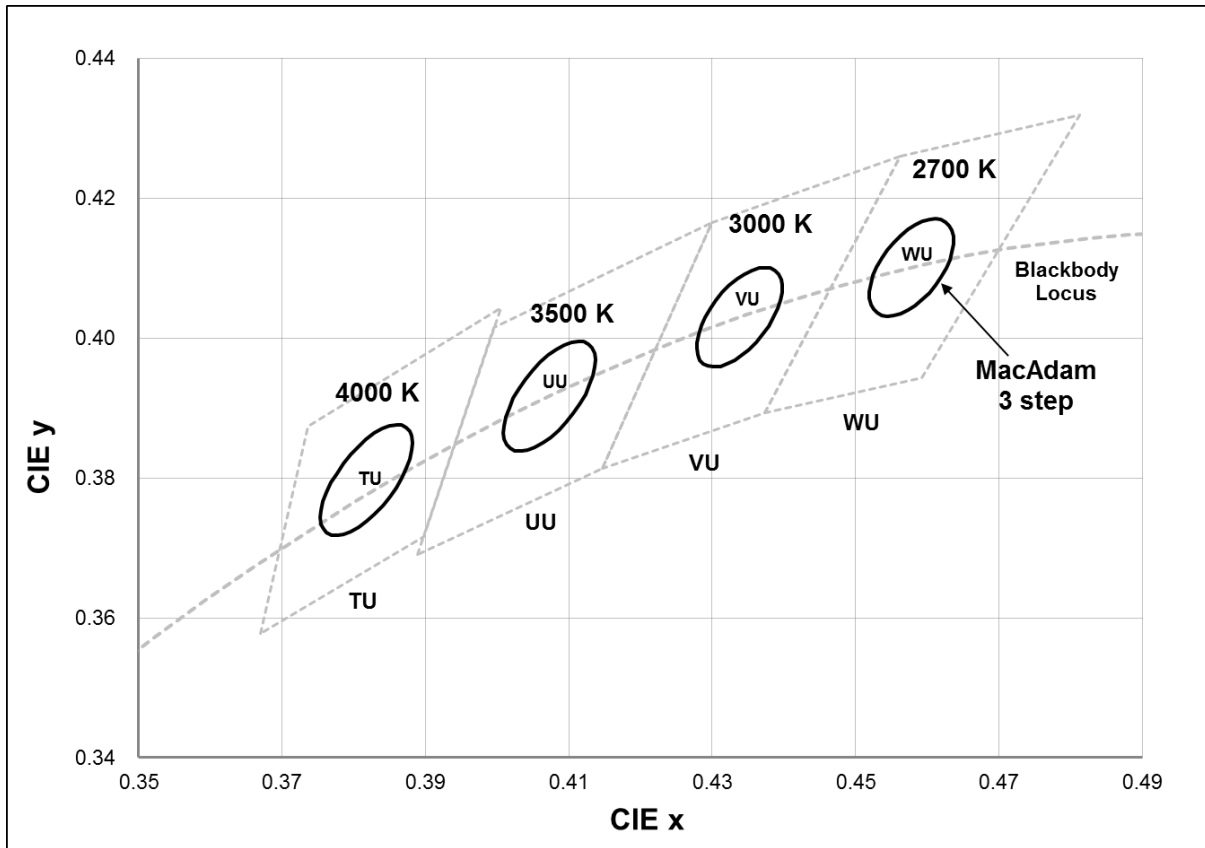
c) Voltage Bins ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$)

Nominal CCT (K)	CRI Min.	Product Code	Voltage Rank	Voltage Bin	Voltage Range (V)
			6E	6A	2.7 ~ 2.9
				AE	2.9 ~ 3.1

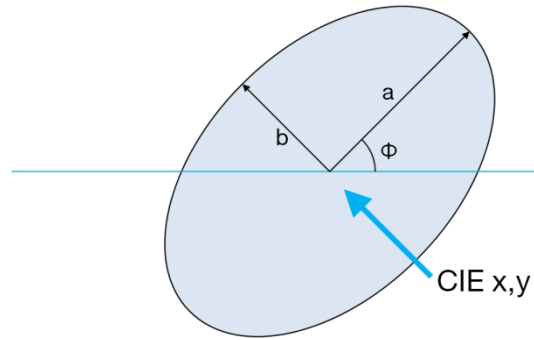
d) Chromaticity Region & Coordinates ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$) : "L" (Single bin for MacAdam 5-step)



d) Chromaticity Region & Coordinates ($I_f = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$) : "U" (Single bin for MacAdam 3-step)



d) Chromaticity Region & Coordinates ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$)



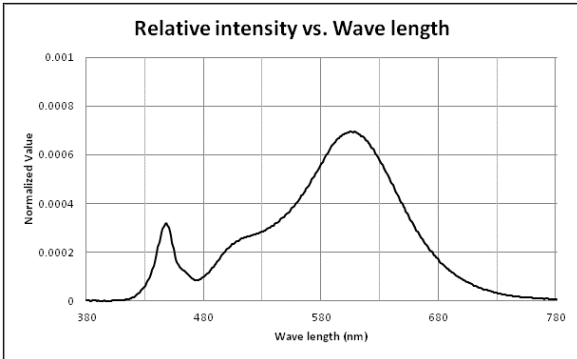
	CCT (K)	Center point		Major-axis	Minor-axis	Rotation
		CIE x	CIE y	a	b	ϕ
3 step (U code)	2700	0.4578	0.4101	0.0081	0.0042	53.70
	3000	0.4338	0.4030	0.0083	0.0041	53.22
	3500	0.4073	0.3917	0.0093	0.0041	54.00
	4000	0.3818	0.3797	0.0094	0.0040	53.72
	5000	0.3447	0.3553	0.0082	0.0035	59.62
	5700	0.3287	0.3417	0.0075	0.0032	59.10
	6500	0.3123	0.3282	0.0067	0.0029	58.57
5 step (L code)	2700	0.4578	0.4101	0.0135	0.0070	53.70
	3000	0.4338	0.4030	0.0138	0.0068	53.22
	3500	0.4073	0.3917	0.0155	0.0068	54.00
	4000	0.3818	0.3797	0.0157	0.0067	53.72
	5000	0.3447	0.3553	0.0137	0.0058	59.62
	5700	0.3287	0.3417	0.0125	0.0053	59.10
	6500	0.3123	0.3282	0.0112	0.0048	58.57

Note: Samsung maintains measurement tolerance of: $C_x, C_y = \pm 0.005$

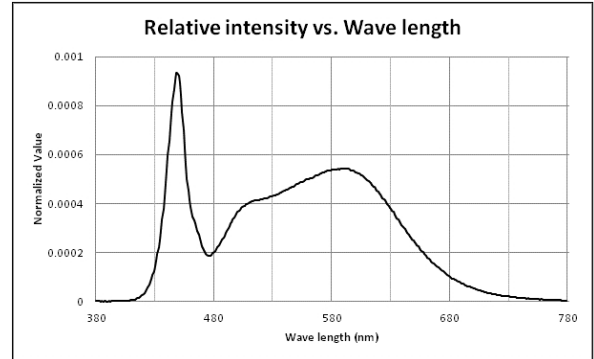
3. Typical Characteristics Graphs

a) Spectrum Distribution ($I_F = 150 \text{ mA}$, $T_s = 85 \text{ }^\circ\text{C}$)

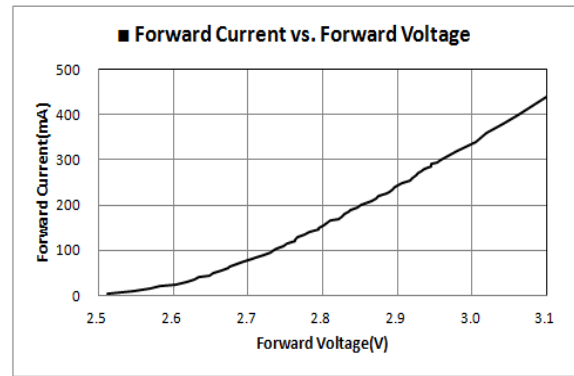
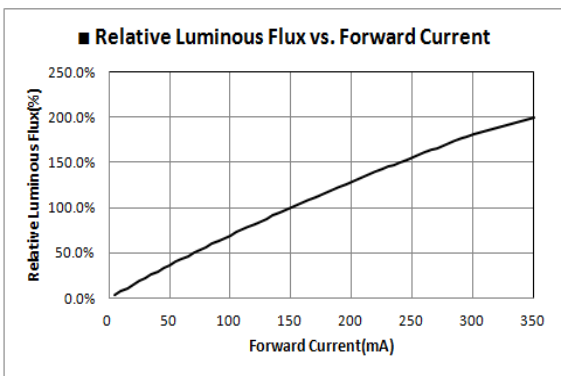
CCT: 2700 K, CRI80



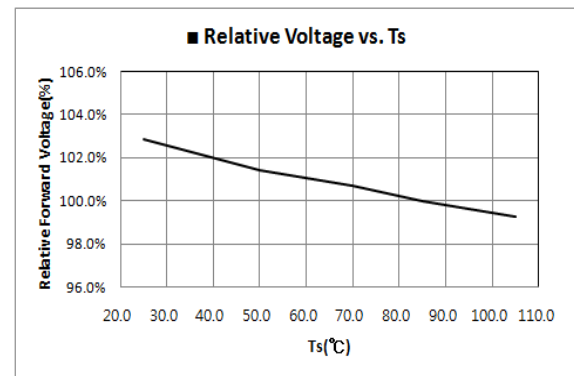
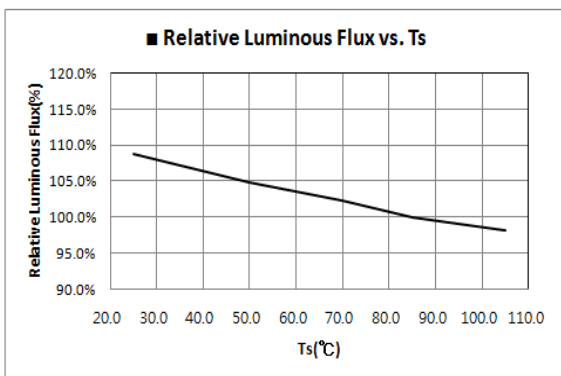
CCT: 5000 K, CRI80



b) Forward Current Characteristics ($T_s = 85 \text{ }^\circ\text{C}$)



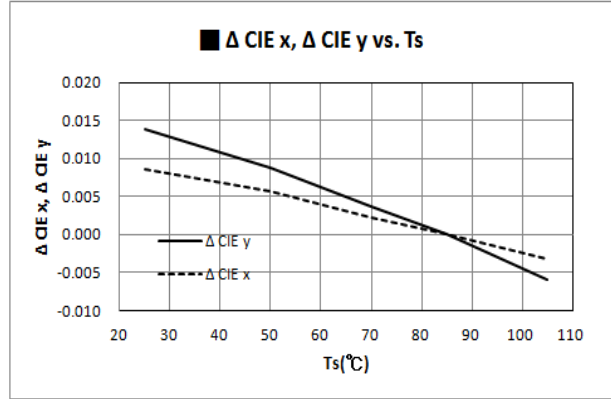
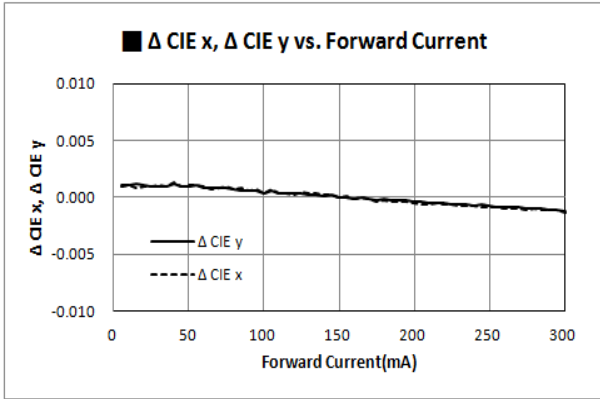
c) Temperature Characteristics ($I_F = 150 \text{ mA}$)



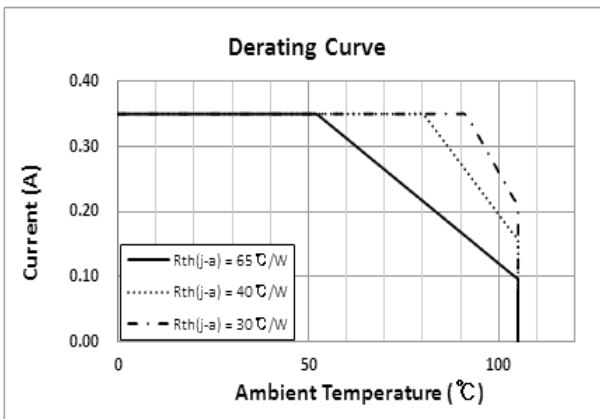
d) Color Shift Characteristics

$T_s = 85\text{ }^\circ\text{C}$

$I_F = 150\text{ mA}$

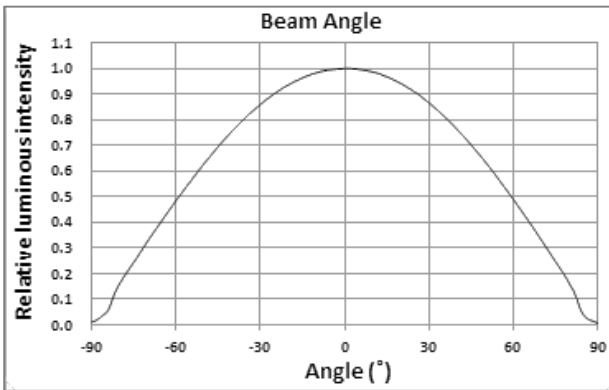


e) Derating Curve



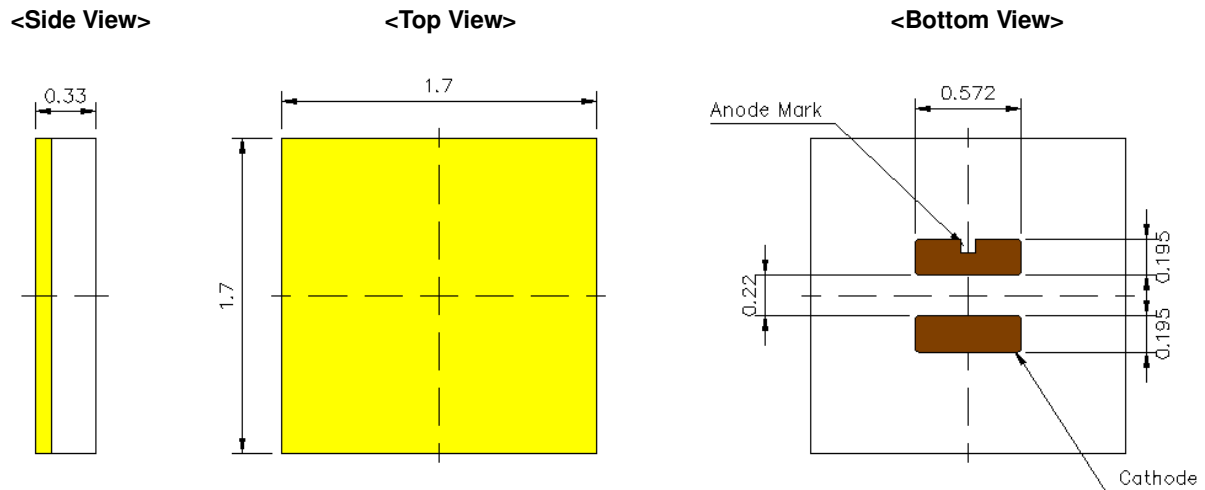
R_{th} is measured after soldering of LED chip on the metal based substrate.
 *metal: aluminum (refer to page 17)

f) Beam Angle Characteristics ($I_F = 150\text{ mA}$)



4. Outline Drawing & Dimension

1. Tolerance is ± 0.10 mm
2. Do not place LEDs with pressure



- Measurement unit: mm
- Tolerance: ± 0.10 mm

Precautions:

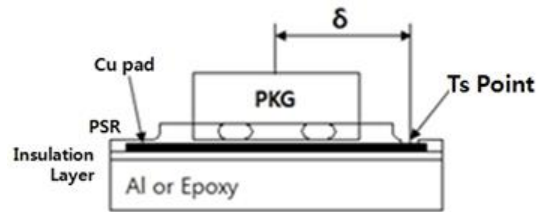
- 1) Pressure on the LEDs will influence to the reliability of the LEDs. Precautions should be taken to avoid strong pressure on the LEDs. Do not put stress on the LEDs during heating.
- 2) Re-soldering should not be done after the LEDs have been soldered. If re-soldering is unavoidable, LED's characteristics should be carefully checked before and after such repair.
- 3) Do not stack assembled PCBs together. Since materials of LEDs is soft, abrasion between two PCB assembled with LED might cause catastrophic failure of the LEDs.

T_s Point & Measurement Method:

Measure nearest point from the center of LED chip (δ) as shown below.

Distance between chip center and T_s point (δ) = 3.5 mm

$T_j = T_s + \text{Power} \times \text{Thermal resistance at } T_s (R_{j-s})$

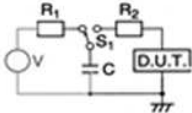


Precautions:

- 4) This LED chip PKG does not contain built-in ESD protection device.
- 5) Pressure on the LEDs will influence to the reliability of the LEDs. Precautions should be taken to avoid strong pressure on the LEDs. Do not put stress on the LEDs during heating.
- 6) Re-soldering should not be done after the LEDs have been soldered. If re-soldering is unavoidable, LED's characteristics should be carefully checked before and after such repair.
- 7) Do not stack assembled PCBs together. Since materials of LEDs is soft, abrasion between two PCB assembled with LED might cause catastrophic failure of the LEDs.

5. Reliability Test Items & Conditions

a) Test Items

Test Item	Test Condition	Test Hour / Cycle
Room Temperature Life Test	25 °C, Derated max current	1000 h
High Temperature Life Test	85 °C, Derated max current	1000 h
High Temperature Humidity Life Test	85 °C, 85 % RH, Derated max current	1000 h
Low Temperature Life Test	-40 °C, DC Derated max current	1000 h
Powered Temperature Cycle Test	-45 °C / 20 min ↔ 85 °C / 20 min, sweep 100 min cycle on/off: each 5 min, Derated max current	100 cycles
Temperature Cycling	-45 °C / 15 min ↔ 125 °C / 15 min → Hot plate 180 °C	500 cycles
High Temperature Storage	120 °C	1000 h
Low Temperature Storage	-40 °C	1000 h
ESD (HBM)	 <ul style="list-style-type: none"> i₁: 10 MΩ i₂: 1.5 kΩ :: 100 pF :: ±5 kV 	5 times
Vibration Test	20~2000~20 Hz, 200 m/s ² , sweep 4 min X, Y, Z 3 direction, each 1 cycle	4 cycles
Mechanical Shock Test	1500 g, 0.5 ms	5 cycles

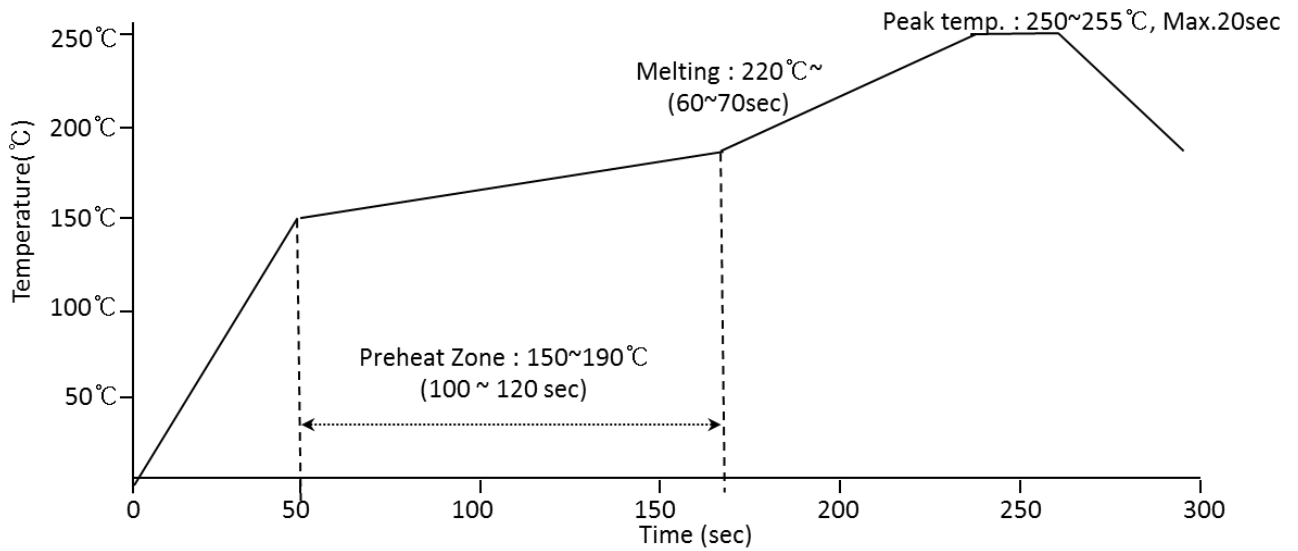
b) Criteria for Judging the Damage

Item	Symbol	Test Condition (T _s = 25 °C)	Limit	
			Min	Max
Forward Voltage	V _F	I _F = Derated max current	Init. Value * 0.9	Init. Value * 1.1
Luminous Flux	Φ _v	I _F = Derated max current	Init. Value * 0.7	Init. Value * 1.1

6. Soldering Conditions

a) Reflow Conditions (Pb free)

Reflow frequency: 2 times max.

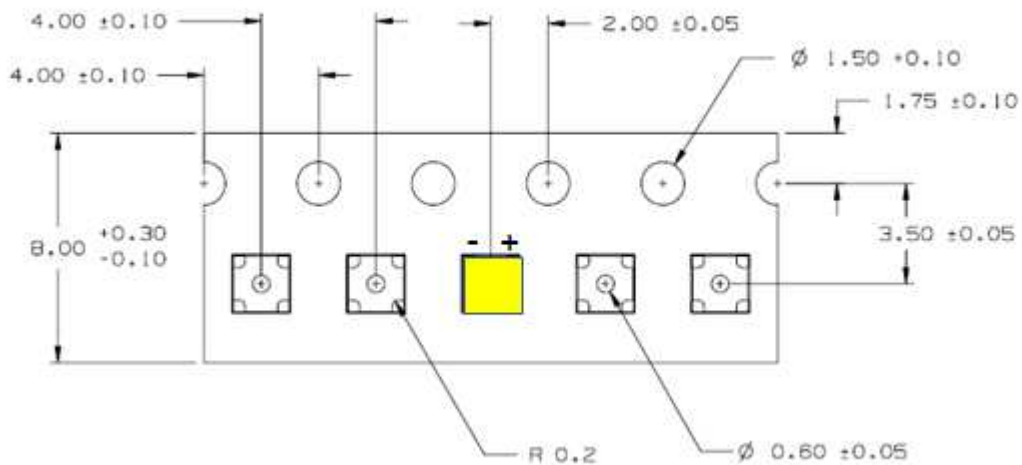


b) Manual Soldering Conditions

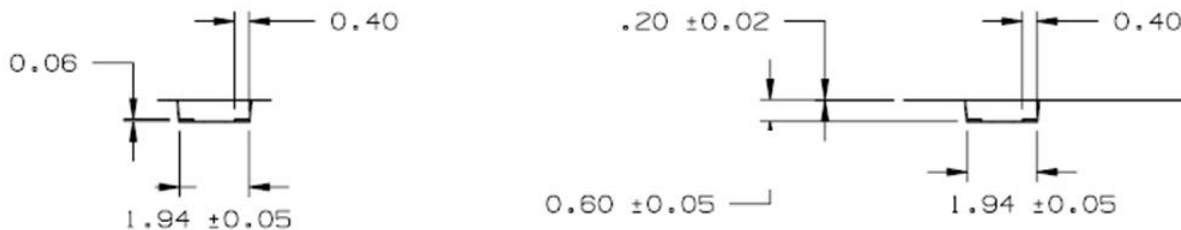
Not more than 5 seconds @ max. 300 °C, under soldering iron

7. Tape & Reel

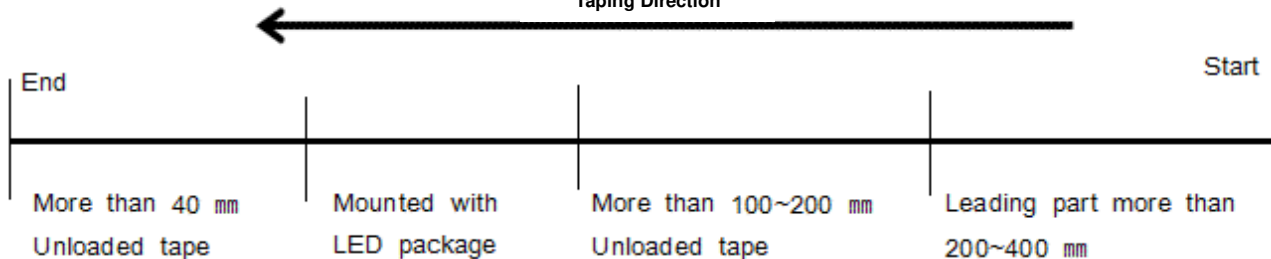
a) Taping Dimension



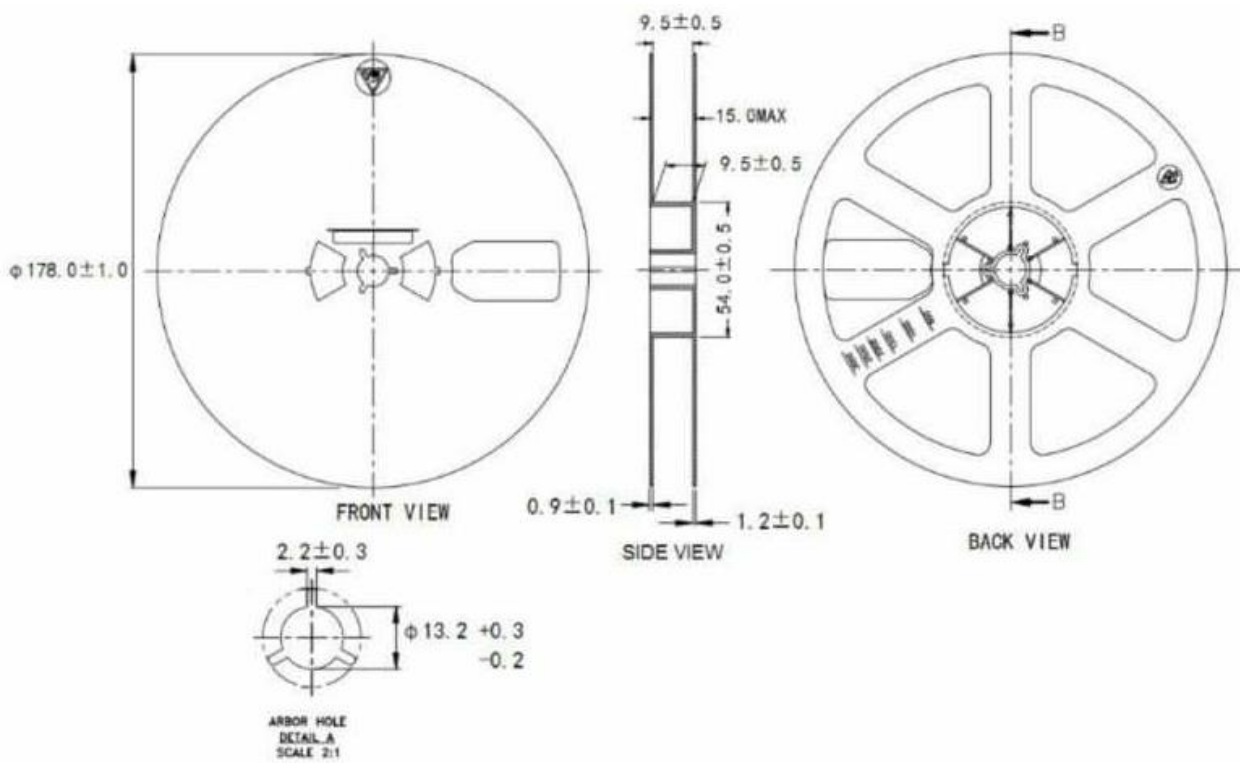
(unit: mm)



Taping Direction



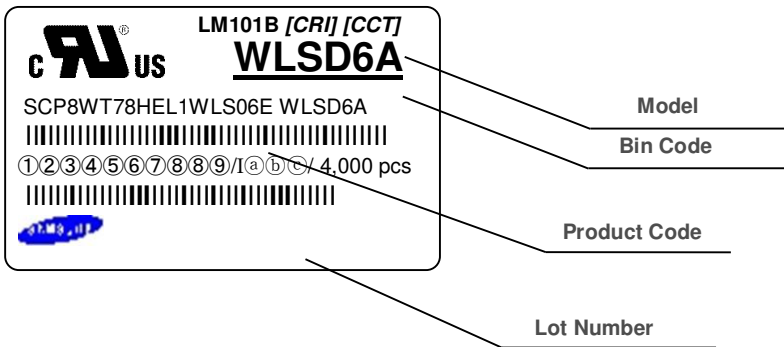
b) Reel Dimension

**Notes:**

- 1) Quantity: The quantity/reel is 4,000 pcs
- 2) Cumulative Tolerance: Cumulative tolerance / 10 pitches is ± 0.2 mm
- 3) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag

8. Label Structure

a) Label Structure



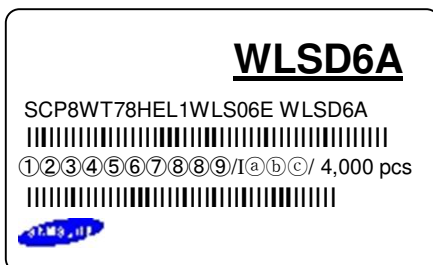
Note: Denoted product code and bin code above is only an example

Bin Code:

- ⒶⒷ: Chromaticity bin (refer to page 10-14)
- ⒸⒹ: Luminous Flux bin (refer to page 7-9)
- ⒺⒻ: Forward Voltage bin (refer to page 11)

b) Lot Number


The lot number is composed of the following characters:



①②③④⑤⑥⑦⑧⑨ / I(a)(b)(c) / 4,000 pcs

- ①② : Production site (GB: Nanchang China)
- ③ : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)
- ④ : Year (Y: 2014, Z: 2015, A: 2016, ...)
- ⑤ : Month (1~9, A, B, C)
- ⑥ : Day (1~9, A, B~V)
- ⑦⑧⑨ : Product serial number (001 ~ 999)

b) Aluminum Vinyl Packing Bag



CAUTION

This bag contains
MOISTURE SENSITIVE DEVICES

LEVEL
2a

1. Shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)
2. Peak package body temperature: 240 °C
3. After this bag is opened, devices that will be subjected to reflow solder or other high temperature processes must be:
 - a. Mounted within 672 hours at factory conditions of equal to or less than 30°C /60% RH, or
 - b. Stored at <10% RH
4. Devices require bake, before mounting, if:
 - a. Humidity Indicator Card is >65% when read at 23±5°C, or
 - b. 2a is not met.
5. If baking is required, devices must be baked for 1 hours at 60±5°C

Note: if device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure,

Bag seal due date: _____
(if blank, see code label)

Note: Level and body temperature by IPC/JEDEC J-STD-020


LM101B [CRI] [CCT]




C[®] AV[®] US

WLS06A

SCP8WT78HEL1WLS06E WLS06A

①②③④⑤⑥⑦⑧⑨/1(a)(b)(c) / 4,000 pcs




■ 주의 사항

이 알루미늄 지퍼 팩은 습기 및 정전기로부터 제품을 보호하기 위하여 제작되었습니다. 개봉 후에는 즉시 솔더 작업을 실시하는 것을 권장합니다.

습기 및 정전기로부터 제품을 보호 하기 위해서 개봉 후 사용하지 않는 자재는 본 팩에 넣어 보관 하시기 바랍니다. 사용하지 않는 자재를 본 팩에 넣을 때는 반드시 동봉된 드라이 팩과 함께 넣고 지퍼부분을 완전하게 밀봉하여 주시기 바랍니다.

■ Important

This Al Zipper bag is designed to protect the enclosed products from moisture and ESD. Once opened, the products should be soldered onto the printed circuit board immediately. When not in use, please do not leave the products unprotected by the Al Zipper Bag. To repack unused products., please ensure the zip-lock is completely sealed with the dry pack left inside.

c) Silica Gel & Humidity Indicator Card inside Aluminum Vinyl Bag

